Title (en)

ADHESIVE COMPOUND AND METHOD FOR ENCAPSULATING AN ELECTRONIC ASSEMBLY

Title (de)

KLEBMASSE UND VERFAHREN ZUR KAPSELUNG EINER ELEKTRONISCHEN ANORDNUNG

Title (fr)

ADHÉSIF ET PROCÉDÉ D'ENCAPSULATION D'UN SYSTÈME ÉLECTRONIQUE

Publication

EP 2638570 A1 20130918 (DE)

Application

EP 11779147 A 20111027

Priority

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Abstract (en)

[origin: WO2012062587A1] The invention relates to the use of an adhesive compound for encapsulating an (opto-)electronic application, containing an organometallically modified polymer created by reacting an elastomer with an organometallic compound, wherein the central atom of the organometallic compound is a metal or metalloid of the 3rd and 4th main groups or 3rd and 4th subgroups.

IPC 8 full level

C09J 109/06 (2006.01); **C09J 153/00** (2006.01); **H01L 23/29** (2006.01)

CPC (source: EP KR)

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Citation (search report)

See references of WO 2012062587A1

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DE 102010043871 A 20101112; CN 201180064864 A 20111027; EP 11779147 A 20111027; EP 2011068822 W 20111027; KR 20137015033 A 20111027; TW 100141033 A 20111110